

Chip Scale Review®

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The Future of Semiconductor Packaging

2017 Editorial Calendar

(Editorial close date: 4/21)

July • August

* indicates show distribution

OSATs: Challenges for revenue growth
High-density advanced packaging solutions for today's OSATs & foundries

Wafer thinning

TSV technologies for next-gen application challenges

Die attach solutions

Performance and cost for 2.5D packaging

3D metrology challenges

3D capacitors for on-chip integration

HVM of chip-on-submount

- **ICEPT 2017**
Harbin, China (Aug 16-19)
- **BiTS China 2017**
Shanghai, China (Sept 7)
- **SEMICON Taiwan ***
Taipei, Taiwan (Sept 13-15)
- **SMTA International ***
Rosemont, IL (Sept 17-21)
- **European MEMS Summit**
Grenoble, France (Sept 20-22)

International directory of IC packaging foundries

Ad Space Close Jun 30 - Ad Materials Close Jul 7

(Editorial close date: 6/9)

September • October

* indicates show distribution

Technology trends in photonics packaging

Lithographic challenges for PLP

Packaging ICs/sensors for automotive applications

High-volume via formation in solid-core glass for IC substrates

Excimer laser ablation for fine RDL routings

Final test

Packaging SiPs/SiP supply chain

Interferometry sensors for metrology applications

Non-destructive 3D X-ray imaging for advanced packaging failure analysis

- **IMAPS 2017 ***
Raleigh, NC (Oct 9-12)
- **IWLPC-International Wafer-Level Packaging Conference & Exhibition ***
San Jose, CA (Oct 24-26)
- **International Test Conference (ITC)**
Fort Worth, TX (Oct 31- Nov 2)
- **MEMS Executive Congress**
Napa Valley, CA (Nov 1-2)
- **SEMICON Europa**
Munich, Germany (Nov 14-17)

Ad Space Close Sep 9 - Ad Materials Close Sep 16

(Editorial close date: 9/1)

November • December

* indicates show distribution

2.5D & 3D ICs

Probe technology for advanced 3D chips

China IC market update

Packaging challenges for automotive applications

Optimization of fan-out die placement

What's now & next in MEMS & Sensors

TCB – Part 2

IC cleaning process

- **3D ASIP Conference ***
Burlingame, CA (Dec 5-7)
- **EPTC 2017**
Singapore (Dec 6-9)
- **SEMICON Japan**
Tokyo, Japan (Dec 13-15)
- **SEMI European 3D Summit ***
Grenoble, France (Jan 22-24, 2018)

International directory of bonding equipment for 2.5D & 3D assembly

Ad Space Close Nov 4 - Materials Close Nov 11

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